

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L6	6	((("5706171") or ("5968606") or ("6081028")).PN.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/02/08 16:36
L7	3752	(438/106).CCLS.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/02/08 16:37
L9	340	7 and (@pd>"20060501")	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/08 18:31
L10	2	("20040126931").PN.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/02/08 18:31
L11	924	(438/122).CCLS.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/02/08 18:31
L12	83	11 and (@pd>"20060501")	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/08 18:31
L13	4012	((heat near2 sink near2 cap) (metal near3 cap) (heat near2 dissipat\$3)) same ((hole via aperture opening) near4 wall)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/08 19:40

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L14	146	13 and (semiconductor same (die chip))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/08 19:20
L15	330	13 and semiconductor	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/08 19:05
L16	4080	((heat near2 sink near2 cap) (metal near3 cap) (heat near2 dissipat\$3) (heat near2 spreader)) same ((hole via aperture opening) near4 wall)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/08 19:20
L17	173	16 and (semiconductor same (die chip))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/08 19:44
L18	833	(438/121).CCLS.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/02/08 19:40
L19	2	18 and (((heat near2 sink near2 cap) (metal near3 cap) (heat near2 dissipat\$3)) same ((hole via aperture opening) near4 wall))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/08 19:41
L20	17	18 and (((heat near2 sink near2 cap) (metal near3 cap) (heat near2 dissipat\$3)) and ((hole via aperture opening) near4 wall))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/08 19:42

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L21	1074	(438/124).CCLS.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/02/08 19:42
L22	12	21 and (((heat near2 sink near2 cap) (metal near3 cap) (heat near2 dissipat\$3)) and ((hole via aperture opening) near4 wall))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/08 19:42
L23	17	21 and (((heat near2 sink near2 cap) (metal near3 cap) (heat near2 cap) (heat near2 sink) (heat near2 dissipat\$3)) and ((hole via aperture opening) near4 wall))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/08 19:44
L24	22415	(((heat near2 sink near2 cap) (metal near3 cap) (heat near2 cap) (heat near2 sink) (heat near2 dissipat\$3)) and ((hole via aperture opening) near4 wall))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/08 19:44
L25	1620	24 and (semiconductor same (die chip))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/08 19:44
L26	1112	25 and (elastomer\$2 polymer\$2 synthetic resin\$4 organic)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/08 19:46
L27	863	26 and fill\$3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/08 19:47

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L28	115	26 and (fill\$3 same encapsulant)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/08 19:48
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